



Material Content Data Sheet



Sales Product Name				BSC011N03LS		Issued		27. July 2015	
MA#				MA001010776					
Package				PG-TDSON-8-7		Weight*		118.96 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.009	0.85	0.85	8485	8485	
leadframe	non noble metal	iron	7439-89-6	0.038	0.03		318		
	inorganic material	phosphorus	7723-14-0	0.011	0.01		95		
	non noble metal	copper	7440-50-8	37.762	31.73	31.77	317434	317847	
wire	noble metal	gold	7440-57-5	0.041	0.03	0.03	344	344	
encapsulation	organic material	carbon black	1333-86-4	0.087	0.07		729		
	plastics	epoxy resin	-	6.156	5.18		51752		
	inorganic material	silicondioxide	60676-86-0	37.112	31.20	36.45	311973	364454	
leadfinish	non noble metal	tin	7440-31-5	1.470	1.24	1.24	12355	12355	
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1391	1391	
solder	noble metal	silver	7440-22-4	0.036	0.03		305		
	non noble metal	tin	7440-31-5	0.029	0.02		244		
	non noble metal	lead	7439-92-1	1.387	1.17	1.22	11659	12208	
heatspreader	non noble metal	iron	7439-89-6	0.011	0.01		95		
	inorganic material	phosphorus	7723-14-0	0.003	0.00		29		
	non noble metal	copper	7440-50-8	11.320	9.52	9.53	95159	95283	
heat sink CLIP	non noble metal	iron	7439-89-6	0.022	0.02		188		
	inorganic material	phosphorus	7723-14-0	0.007	0.01		56		
	non noble metal	copper	7440-50-8	22.292	18.74	18.77	187389	187633	
*deviation	< 10%		Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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